

HSM124S

Silicon Epitaxial Planar Diode for Switching

HITACHI

ADE-208-041D (Z)

Rev. 4

Aug. 1995

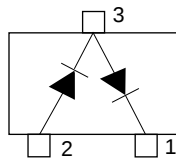
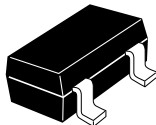
Features

- Low reverse current.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM124S	A1	MPAK

Pin Arrangement



(Top View)

- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1
- Anode 2

Absolute Maximum Ratings*² (Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	80	V
Reverse voltage	V_R	85	V
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*1}	4	A
Average forward current	I_O	100	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

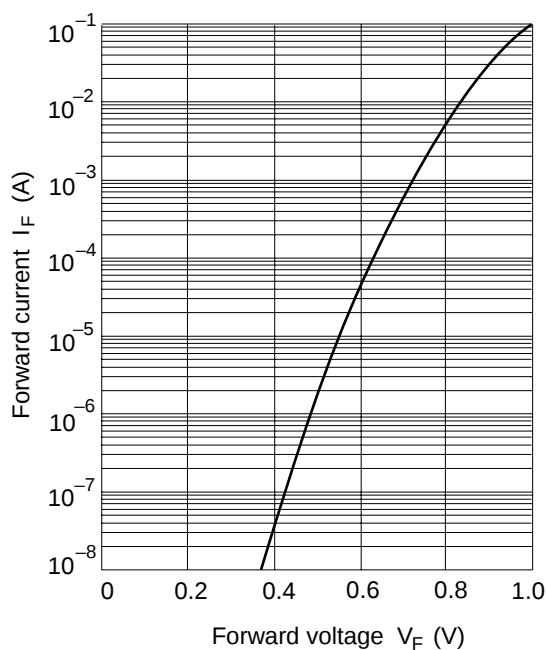
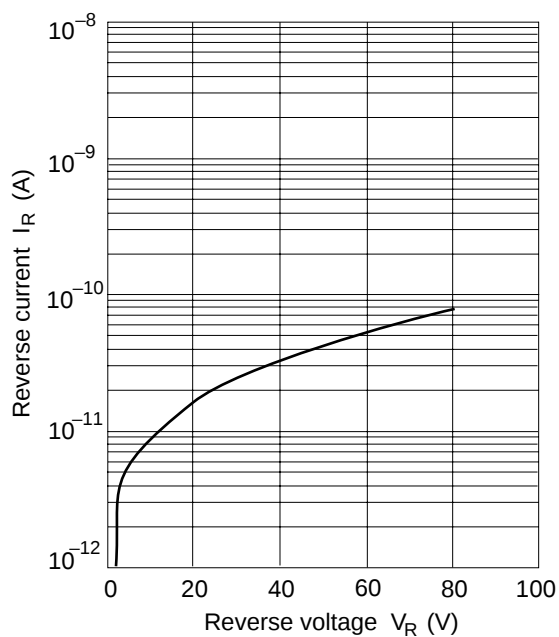
Notes: 1. Within 1μs forward surge current.

2. Per one device

Electrical Characteristics* (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	1.0	V	$I_F = 10\text{mA}$
	V_{F2}	—	—	1.0		$I_F = 50\text{mA}$
	V_{F3}	—	—	1.2		$I_F = 100\text{mA}$
Reverse current	I_R	—	—	0.01	μA	$V_R = 80\text{V}$
Capacitance	C	—	—	4.0	pF	$V_R = 0\text{V}$, f = 1MHz
Reverse recovery time	t_{rr}	—	—	100	ns	$I_F = 10\text{mA}$, $V_R = 6\text{V}$, $R_L = 50\Omega$

Note: Per one device

**Fig.1 Forward current Vs. Forward voltage****Fig.2 Reverse current Vs. Reverse voltage**

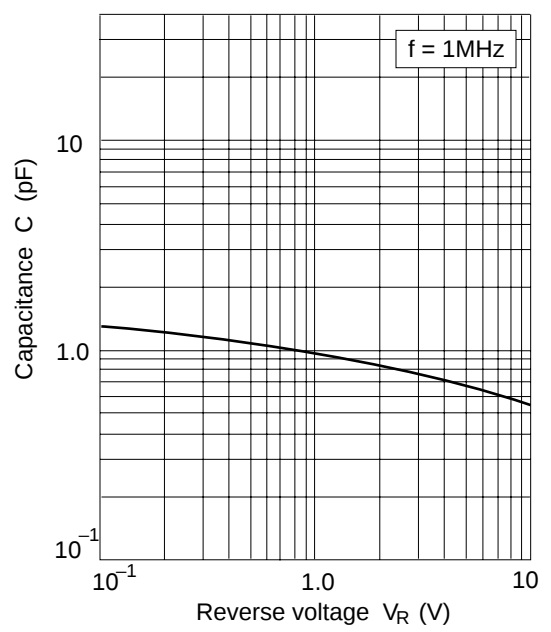
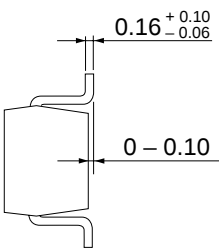
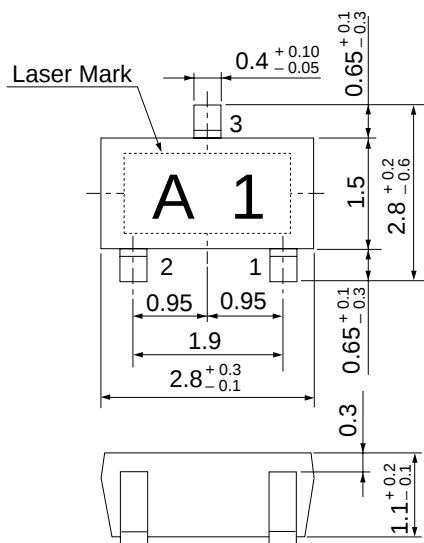


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1
- Anode 2

HITACHI Code	MPAK(1)
JEDEC Code	—
EIAJ Code	SC-59A
Weight (g)	0.011

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